FORM 1			- 1	(FOR OFFICE USE ONLY)					
THE PATENTS ACT 1970				Application No:					
(39 of 1970) &				Filing Date:			M 1100 tu		
The Patent Rules, 2003				Amount	of fee paid:				
APPLICATION FOR GRANT			OF	CBR No	<b>)</b> :		700164397		
PATENT				Signature:					
(See section 7, 54 &	135, and ru	ıle 20	(1))						
		App	licatio	n No.		201841030070			
		Filin	iling date:			10/08/2018			
		Amount of Fee paid:			id:	8800/			
CBR No		l No:		-	22354				
		Sign	ature	-					
1. APPLICANT'S F	REFERENC	E/				·			
IDENTITY NUMB	ER. (AS A	LLO	TED E	3Y			1 8/		
OFFICE)	-			ŀ			1/10/		
2. TYPE OF APPLI	CATION [	Please	e tick (	(🗸) at 1	he appropr	iate category]	4		
Ordinary (✓)		Con	ventio	n ()		PCT-NP ()			
Divisional () Pate	nt of	Divi	sional	()   Pa	tent of	Divisional ()	Patent of		
Add	ition ()			Ad	dition ()		Addition ()		
3A. APPLICANTS									
Name in Full Nationality			y Country of Residence		Address of	Address of Applicant			
<u> </u>				-	ALVA'S	INSTITU	UTE OF		
ALVA'S				ENGINEERING AND TECHNOLOGY					
EDUCATION	Indian		India						
FOUNDATION		1					RI, DAKSHINA KANNADA		
1			-574225, KARNATAKA, INDIA						
3B. CATEGORY O	F APPLIC	ANT	Please	e tick (					
Natural Person (✓)					<u> </u>				
ĺ						Other	rs ( )		
4. INVENTOR(S)	Please tick (	✓) at	t the a	ppropr	iate categor	yl			
Are all the invento	r(s) same a	s the	Yes	0	No (	<del>√</del> )			
applicant(s) named a				-					
If NO furnish the det		vento	rs		<u> </u>				
raimon del	2.15 0. 110 11		ountr						
	Nationalit		_	· 6					
Name in Full	y		eside	Address of Applicant					
	"		nce						
				ALVA	'S INSTIT	CUTE OF I	ENGINEERING		
DACUME IZ D	T	<sub> </sub>	ai.	AND	TECHN		SHOBHAVANA		
RASHMI K. R Indian		In	dia	CAMP	US, MIJAF	R, MOODBIDI	RI, DAKSHINA		
					•	25, KARNAT	-		
				ALVA	'S INSTIT	TUTE OF I	ENGINEERING		
JAYARAMA A	Indian	I	dia	AND	TECHN	OLOGY S	SHOBHAVANA		
UNINKAWA A	muian	111	นเส	CAMP	US, MIJAF	k, MOODBIDI	RI, DAKSHINA		
				KANN	ADA - 5742	25, KARNATA	AKA, INDIA		

RICHARD PINTO	Indian	India	ALVA'S INSTITUTE OF ENGINEERING AND TECHNOLOGY SHOBHAVANA CAMPUS, MIJAR, MOODBIDRI, DAKSHINA KANNADA - 574225, KARNATAKA, INDIA
SIDDHARTHA P. DUTTAGUPTA	Indian	India	INDIAN INSTITUTE OF TECNOLOGY BOMBAY, POWAI, MUMBAI - 400076, MAHARASHTRA, INDIA
SHRIGANESH PRABHU	Indian	India	TATA INSTITUTE OF FUNDAMENTAL RESEARCH, MUMBAI - 400005, MAHARASHTRA, INDIA

	"A PRO	OF THE INV	ABRICAT	•				
	· · · · · · · · · · · · · · · · · · ·			Name			. <u>.</u>	
				Mobile no.			<u>.</u>	
	7. ADDRESS FOR SERVICE OF APPLICANT IN INDIA			Name			ALVA'S EDUCATION FOUNDATION	
				Postal Address		ENG TECT SHO: MIJA DAK 57422	ALVA'S INSTITUTE OF ENGINEERING AND TECHNOLOGY SHOBHAVANA CAMPUS, MIJAR, MOODBIDRI, DAKSHINA KANNADA - 574225, KARNATAKA, INDIA	
				Telephone N		-		<del></del>
				Mobile No.	0989	09892818760/ 09920818760		
				Fax No.			8 - 262726	
			·	E-Mail ID	il ID rpin		to1942@gmail.com	
_		SE OF APPLIC						
/201841030070/Form	Country Application Filing number date			Name of applicant	th		IPC (as the country)	classified in convention
I \				Not Applic				
3007(		CASE OF PO ATIONAL A '(PCT)				-		
3410;	Internation Applicable		tion numl	oer : Not	Internatio	nal filin	g date : No	Applicable
2018	PARTIC	CASE OF ULARS OF OI	RIGINAL (I	FIRST) APPL	ICATION			
5/2 	Original	(first) appli	cation nun	nber : Not	Date of	filing	of Orig	inal (first)
3/5812				2				
10-Aug-2018/58122/2	OFFIC	<u>E CHEN</u>	NAI	10/68	/ <u> </u>	1.4	40	· · · · · · · · · · · · · · · · · · ·
10-7					c			

Applicable	application: Not Applicable
11. IN CASE OF PATENT OF ADDIT	•
PARTICULARS OF MAIN APPLICANT OR PA Main application/ Patent Number : Not	TENT Date of Filing of main application: Not
Applicable Patent Number : Not	Applicable
i)Declaration by the inventors (In case the applicant is an assignee: the inventors upload the assignment or enclose the assignment or assignment by post/electronic transmission duly auth We, the above named inventors are the true and first the applicants herein are our assignee or legal represe (a)Date:23.07.2018 (b)Signature of the inventors: (c)Names:	with this application for patent or send the tenticated within the prescribed period) to inventors for this invention and declare that
	Richard Pinto
ii)Declaration by the applicant:  I, the applicant hereby declare that:-  I am in possession of the above mentioned inve  The provisional/complete specification rela application.	ntion.
☐ The invention as disclosed in the specification	nt authority shall be submitted by us before
☐ I am the assignee or legal representative of true☐ The application or each of the application, part first application in convention country/countrie	and first inventors. iculars of which are given in Para 5 was the
I claim the priority from the above mentioned state that no application for protection in res convention country before that date by me/us title.	applications filed in convention country and spect of the invention had been made in a
My application in India is based on internat Treaty (PCT) as mentioned in Para-9.	ional application under Patent Cooperation
<ul> <li>The application is divided out of our application and pray that this application may be treated a undersection 16 of the Act.</li> </ul>	

☐ The said invention is an improvement in or modification of the invention particulars of

which are given in Para-11

	· · · · · · · · · · · · · · · · · · ·						
12 FOLLOWING AD		TO SUMMER OF THE A DIST T	CATION				
	E THE ATTACHMEN	TS WITH THE APPLI	CATION				
(a) Form 2	Details	r	Damada				
Item	Details	Fee	Remarks				
Complete/ Provisional Specification #	No. of Pages: 8						
No. of Claims	No. of claims: 1	No of claims: 1					
110. or Glanns	No. of Pages : 2						
Abstract	No. of Pages : 1						
No. of Drawings	No. of drawings : 6	'					
<b>.</b>	No. of pages : 14						
# In case of a complete specification, if the applicant desires to adopt the drawings filed with his provisional specification as the drawings or part of drawings for the complete specification under rule 13(4), the number of such pages filed with the provisional specification are required to mentioned here.  (b) Complete specification (in confirmation with the international application)/ as amended before the International preliminary Examination Authority (IPEA), as applicable (2 copies).  (c) Sequence listing in electronic format.  (d) Drawing (in confirmation with the international application)/ as amended before the International preliminary Examination Authority (IPEA), as applicable (2 copies).  (e) Priority document (s) or a request to retrieve the priority document(s) from DAS (Digital Access Service) if the applicant had already requested the office of first filing to make the priority document(s) available to DAS.  (f) Translation of priority document/ Specification/ International Search Report/ International Preliminary Report on Patentability.  (g) Statement and Undertaking on Form 3.  (h) Declaration of Inventor ship on Form 5.  (i) Power of Attorney.  (j) Total Fee ₹							
23 <sup>rd</sup> day of July, 2018.  Signatures	we /	Civirman	(R).				
Alva's Education Foundation Alva's Education Foundation							
2 of the Rhit							
Rashmi K. R	Jayarama	a A Richa	ard Pinto				
Lidant DouGue shablu							
Siddhartha P. Du		Shriganesh Prabhu					
To, The Controller of Patents, Patent Office Chennai, Chennai – 600 032.							

FORM 2 THE PATENTACT 1970 (39 of 1970)



The Patents Rules, 2003 COMPLETE SPECIFICATION (See section10 and rule 13)

TITLE OF THE INVENTION

### "A PROCESS FOR FABRICATION OF P(VDF-TrFE) PIEZOELECTRIC BEAMS AND CANTILEVERS AS VIBRATION SENSORS AND ENERGY HARVESTERS"

APPLICANT'S NAME AND ADDRESS

#### **ALVA'S EDUCATION FOUNDATION**

INDIAN NATIONAL

#### **ADDRESS**

ALVA'S INSTITUTE OF ENGINEERING AND TECHNOLOGY, SHOBHAVANA CAMPUS, MIJAR, MOODBIDRI, DAKSHINA KANNADA - 574225, KARNATAKA, INDIA

Dated this the 23rd day of July, 2018

#### F O R M 3 THE PATENTS ACT, 1970 (38 OF 1970)



# The Patents Rules, 2003 STATEMENT AND UNDERTAKING UNDER SECTION 8 (See section 8 rule 12)

1. Name of	the Applicant		FOUNDATIO JAYARAMA PINTO add INSTITUTE AND SHOBHAVA MIJAR, DAKSHINA KARNATAK SIDDHARTH addressed at OF TECN POWAI, M MAHARASH SHRIGANES addressed at OF FUNDAM MUMBAI MAHARASH hereby declar made any same/subs	A and I dressed at OF ENGINER TECH NA MOCKANNADA - A, HA P. DUTA INDIAN	II K. R, RICHARD ALVA'S NEERING NOLOGY, CAMPUS, ODBIDRI, 574225, INDIA, FAGUPTA ISTITUTE BOMBAY, 400076, OIA and PRABHU ISTITUTE SEARCH, 400005, DIA do have not in for the one same	
			same/substantially the same invention outside India			
	dress and natio	nality of the	joint applicant	N.A.		
Name of the country	Date of application	Application No.	Status of the application	Date of publication	Date of grant	
NA	NA	NA	NA	NA	NA	

3. Name and address of the assignee	Not Applicable
4. To be signed by the applicant or his authorized registered patent agent.	(a) Date: 23.07.2018 (b) Signature of the inventor:
	·

5. Name of the natural person who has signed	Rashmi K. R  Jayarama A  Richard Pinto  Siddhartha P. Duttagupta  Shriganesh Prabhu Markin.	man indation (F
	Shriganesh Prabhu	
	Date: 23.07.2018	

To The Controller of Patents, The Patent Office, at Chennai

- I. Rashmi K. R
- Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- Shriganesh Prabhu
- 6. Alva's Education Foundation

#### **ABSTRACT**

The process for fabrication of poly (vinylidenefluoride-co-trifluoroethylene) piezoelectric beams and cantilevers comprises cleaning, etching and spinning methods. The present process utilizes silicon wafer as a starting substrate material that is cleaned and oxidized for growth of silicon dioxide, spun with positive photo resist followed by backside patterning to define device regions. The process also uses spinning of positive photo resist for patterning and etching of chrome-gold layer and poly (vinylidenefluoride-co-trifluoroethylene) layer to define cantilevers and beams followed by again spinning of positive photo resist for patterning and etching of chrome-gold layer to define contacts. Further the process utilizes etching of silicon dioxide from the backside of the silicon wafer to release beams and cantilevers. The present invention uses piezoelectric material poly (vinylidenefluoride-co-trifluoroethylene) cantilevers and beams as energy harvesters and vibration sensors.

Dated this 23RD day of JULY, 2018

Signature(s)

Richard Pinto

Siddhartha P. Duttagupta

Shriganesh Prabhu

Chairman

Alva's Education Foundation (R)

- I. Rashmi K. R
- 2. Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

## TITLE: A PROCESS FOR FABRICATION OF P(VDF-TrFE) PIEZOELECTRIC BEAMS AND CANTILEVERS AS VIBRATION SENSORS AND ENERGY HARVESTERS

#### FIELD OF INVENTION

The present invention relates to field of Electromechanics. Specifically, the present invention relates to a process for fabrication of poly (vinylidenefluoride-co-trifluoroethylene) (P (VDF-TrFE) piezoelectric beams and cantilevers as vibration sensors and energy harvesters. Particularly, the present process contains cleaning, etching and spinning. The present process uses piezoelectric material P (VDF-TrFE) as energy harvester and vibration sensor.

#### BACKGROUND OF THE INVENTION

The idea of vibration detection and power generation using piezoelectric materials is well-known. For low frequency (<1000Hz) vibration detection and energy harvesting, poly (vinylidenefluoride-co-trifluoroethylene) (P (VDF-TrFE)) co-polymers have become important due to their large piezoelectric coefficient and low spring constant. However, fabrication of cantilevers and beams of P (VDF-TrFE) co-polymers has been extremely difficult due to its extreme sensitivity to process chemicals.

The piezoelectric based vibration sensors could be integrated with wireless sensor node for in-vitro applications such as monitoring patient health like heartbeat. Piezoelectric based vibration energy harvesters in the form of beams and cantilevers, have wide ranging potential such as in-vivo applications for powering pacemakers etc. The in-vivo applications however, are challenging due to the bio-compatibility issues of the energy harvester. Nevertheless, the first set of in-vitro applications appear to be realistic.

Vibration monitoring sensors and associated signal conditioning as an integral part of industrial predictive maintenance programs is increasingly becoming important for maintenance and plant engineers for monitoring overall health of the machinery as an effective strategy for reducing downtime. Vibration monitoring sensors are widely used because of their ability to detect and

- 1. Rashmi K, R
- 2. Javarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prahhu
- 6. Alva's Education Foundation

diagnose a wide variety of machinery faults, such as bearing faults, gear problems, misalignment, mass imbalance, and others, on a wide variety of rotating machinery, and its relative ease of integration with portable data collectors, online vibration monitoring systems, PLC's, and Plant Information (PI) systems.

Various energy harvesters have been devised in prior art some of the measures are as follows:

US20160197261 relates to an energy harvester for converting vibration energy into electrical energy and harvesting the electrical energy, the energy harvester comprising: a base; a clamping structure which is supported by the base and is spaced apart from the base; an elastic member which is disposed between the base and the clamping structure and allows the clamping structure to be elastically moved relative to the base; and a cantilever structure comprising: a cantilever beam having one side which is fixed to the clamping structure and the other side which is elastically bendable; and a mass body which is disposed on the cantilever beam.

US20150203345 relates to a polymer anchored microelectromechanical system (MEMS) cantilever, comprising a base and a cantilever beam projecting from the base, wherein the cantilever beam consists of a piezo layer sandwiched between an inorganic material structural layer and an inorganic material encapsulating and immobilizing layer and a pair of electrical contacts formed in the encapsulating and immobilizing layer in contact with the piezo layer and wherein the base consists of polymer.

A known publication by Ethem Erkan Aktakka et al (2011) in Transducers'11, Beijing, China, June 5-9, 2011, discloses design, fabrication, and testing of a thinned-PZT/Si unimorph cantilever for vibration energy harvesting. This harvester utilizes thinning of bulk-PZT pieces bonded to an SOI wafer, and takes advantage of the similar thermal expansion between PZT and Si to minimize beam bending due to residual stress.

Another known publication by Pierre-Henri Ducrot et al (2016) in Scientific Reports, 2016; 6: 19426 refers a systematic optimization of processing conditions of PVDF-TrFE piezoelectric thin films, used as integrated transducers in organic MEMS resonators. Indeed, despite data on electromechanical properties of PVDF found in the literature, optimized processing conditions

- Rashmi K R
- 2. Javarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

that lead to these properties remain only partially described. In this work, a rigorous optimization of parameters enabling state-of-the-art piezoelectric properties of P (VDF-TrFE) thin films has been performed via the evaluation of the actuation performance of MEMS resonators. Conditions such as annealing duration, poling field and poling duration have been optimized and repeatability of the process has been demonstrated.

Yet another known prior art by Sharon Roslyn Oh et al (2013) in Journal of Micromechanics and Microengineering, Volume 23, Number 9, discuss the fabrication of arrays of piezoelectric P(VDF-TrFE) MEMS cantilevers, batch fabricated via wafer level surface micromachining techniques. In this process Water-soluble poly (vinyl alcohol) (PVA) was selected as the sacrificial layer, due to its compatibility with the processing of P (VDF-TrFE).

Even another known publication by N. Snis et al (2008) in Sensors and Actuators A: Physical, Volume 144, Issue 2, 15 June 2008, Pages 314–320 refers a monolithic multilayer structure of the piezoelectric co-polymer P (VDF-TrFE) by using successive spin coating and electrode evaporation.

The present invention overcomes the inadequacies of the prior art by providing a fabrication process for energy harvester.

#### OBJECT OF THE PRESENT INVENTION

One or more of the problems of the conventional prior art may be overcome by various embodiments of the present invention.

Accordingly, the primary object of the present invention is to provide a process of fabrication.

It is one object of the present invention, wherein the said process fabricates poly (vinylidenefluoride-co-trifluoroethylene) (P (VDF-TrFE)) piezoelectric beams and cantilevers.

It is another object of the present invention, wherein the said process contains cleaning, etching and spinning methods.

- Rashmi K. R
- Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

It is even another object of the present invention, wherein the said process contains piranha cleaning and rinsing with isopropyl alcohol, followed by spinning of P (VDF-TrFE).

It is even another object of the present invention, wherein the said P (VDF-TrFE) is a piezoelectric material which is patterned and etched to release free beams and cantilevers as vibration sensors and energy harvesters.

#### SUMMARY OF THE PRESENT INVENTION

According to the basic aspect of the present invention there is provided a process for fabrication of poly(vinylidenefluoride-co-trifluoroethylene) (P(VDF-TrFE)) piezoelectric beams and cantilevers as vibration sensors and energy harvesters comprising: cleaning of silicon wafers, growing of Silicon dioxide (SiO<sub>2</sub>) by wet oxidation, spinning positive photo resist on both sides and backside patterning, etching backside SiO<sub>2</sub> using buffered hydrofluoric acid, stripping front side and back side of positive photo resist using acetone, etching silicon by means of tetra methyl ammonium hydroxide, cleaning of substrate by piranha, rinsing with isopropyl alcohol and pre baking for 15 min at 150°C, spinning the said P(VDF-TrFE), sequential thermal evaporation of Chrome-Gold (Cr-Au), patterning of Cr-Au using, etching Cr-Au using Cr-Au etchant, etching P(VDF-TrFE) by plasma ash using Cr-Au as etch mask, patterning of Cr-Au for contacts, etching Cr-Au using Cr-Au etchant, stripping positive photo resist by UV exposure and developer and etching SiO<sub>2</sub> from backside by plasma etching to free the beams and cantilevers.

It is one aspect of the present invention, wherein the said piranha is cleaned by mixing sulfuric acid and hydrogen peroxide in 3:1 ratio.

It is one aspect of the present invention, wherein the said spinning of P (VDF-TrFE) is done at least at 300 rpm for 10 sec and 1000 rpm for 30 sec and spinning of photo resist is done at least at 3000 rpm for 30 sec.

- Rashmi K. R
- 2. Jayarama A
- 3. Richard Pinto
- 4, Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

#### BRIEF DESCRIPTION OF DRAWINGS

Figure 1 illustrates schematic representation of poly (vinylidenefluoride-co-trifluoroethylene) piezoelectric cantilever, wherein a represents P (VDF-TrFE), b represents Cr-Au IDE, c represents Fixed End, according to present invention.

Figure 2 illustrates schematic representation of poly (vinylidenefluoride-co-trifluoroethylene) piezoelectric beam, wherein a represents P (VDF-TrFE), b represents Cr-Au IDE, c represents Fixed End, according to present invention.

Figure 3 illustrates P (VDF-TrFE) cantilever or beam as vibration sensor, according to present invention.

Figure 4 illustrates poly (vinylidenefluoride-co-trifluoroethylene) cantilever or beam as energy harvester, wherein d represents silicon wafer 2 inch, e represents 2.5 micron thick P(VDF-TrFE), f represents Cr/Au contact, according to present invention.

Figure 5 (a- o) illustrates the diagrammatic representation of process flow of for fabrication of cantilevers and beams, wherein from figure 5 (i - o) 1 represents cantilever and 2 represents beam, according to present invention.

Figure 6 illustrates the flow chart of process flow of for fabrication of cantilevers and beams, according to present invention.

- 1. Rashmi K. R
- 2. Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- Shriganesh Prabhu

6. Alva's Education Foundation

DETAILED INVENTION WITH REFERENCE TO DESCRIPTION OF ACCOMPANYING DRAWINGS

The preferred embodiment of the present invention will now be explained with reference to the accompanying drawings. It should be understood however that the disclosed embodiments are merely exemplary of the invention, which may be embodied in various forms. The following description and drawings are not to be construed as limiting the invention and numerous specific details are described to provide a thorough understanding of the present invention, as the basis for the claims and as a basis for teaching one skilled in the art how to make and/or use the invention. However in certain instances, well-known or conventional details are not described in order not to unnecessary obscure the present invention in detail.

With reference to figures 1 - 4, the present invention of a process for fabrication of poly(vinylidenefluoride-co-trifluoroethylene) P(VDF-TrFE) piezoelectric cantilevers and beams as vibration sensors and energy harvesters comprises the process of cleaning, etching, spinning of P(VDF-TrFE) and striping positive photo resist to free beams and cantilevers. These cantilevers and beams can be used as vibration sensors and energy harvesters which are shown in the Figures 3 and 4, respectively.

The said process of fabrication is initiated by cleaning of silicon wafer that is 2 inch diameter and single side polished. Silicon dioxide on cleaned Silicon wafer is allowed to grow by wet oxidation method. The said wafers undergo spinning of positive photo resist on both sides of wafer followed by backside patterning to define device regions. The said SiO<sub>2</sub> is etched from backside using buffered hydrofluoric acid, the composition is ammonium fluoride: hydrofluoric acid in 5:1 ratio. The positive photo resist is stripped from front side and backside by using acetone. The said silicon wafer is then etched fully, about 275 microns depth at the device regions from backside by tetra methyl ammonium hydroxide.

In one process of the present invention, the silicon wafer is cleaned by piranha which is a mixture of sulfuric acid and Hydrogen peroxide in 3:1 ratio. The said silicon wafer is rinsed with

- Rashmi K. R
- Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

Isopropyl Alcohol and pre-baked for 15 minutes at 150°C and followed by spinning 2.5µm thick P (VDF-TrFE) at 300 rpm for 10sec and 1000 rpm for 30sec and post baked at 120°C.

In another process of the present invention, the said process stipulates sequential thermal evaporation of Chrome-Gold (Cr-Au) whereas Cr is 10nm thick and Au is 140nm thick. The said positive photo resist is spun at 1.5 µm thick (3000 rpm for 30 sec) and Cr-Au is patterned using cantilever and beam mask. The said Chrome-Gold is etched using Chrome-Gold etchant. The said P (VDF-TrFE) is then etched using plasma asher and simultaneously positive photo resist is stripped.

In yet another process of the present invention, the positive photo resist is spun at 3000 rpm for 30 sec and Cr-Au is patterned using contacts mask. The said Cr-Au is again etched using Cr-Au etchant. Positive photo resist is stripped by UV exposure and developer. Finally SiO<sub>2</sub> is etched from backside by plasma etching to free the beams and cantilevers.

The detailed process flow for fabrication of cantilevers and beams is shown below, which is only illustrative and should not be construed as limitation. With reference to figure 5 (a- o) and figure 6, the said process flow comprises:

- 1) Cleaning of silicon wafers with following features: 2 inch diameter, Single Side polished (SSP) and resistivity: 4-7 ohm-cm.
- Growth of silicon dioxide (1 micron) by Wet oxidation.
- 3) Spin positive photo resist at the rate of 300 rpm for 10 sec, 3000 rpm for 30 sec on both sides of the wafer and backside patterning.
- 4) Etching Backside SiO<sub>2</sub> using BHF 5:1.
- 5) Strip front side and backside positive photo resist using acctone.
- 6) Etch silicon wafer fully from backside by tetra methyl ammonium hydroxide (about 275 microns) followed by piranha cleaning.
- 7) Rinse with isopropyl alcohol and pre bake for 15 min at 150°C followed by spinning ~2.5µm thick P (VDF-TrFE) (300 rpm for 10sec and 1000 rpm for 30sec).

- Applicants:
- I. Rashmi K. R. 2. Javarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation
- 8) Sequential thermal evaporation of Cr-Au (Cr-10 nm and Au-140 nm).
- 9) Spin positive photo resist on front side at the rate of 300 rpm for 10 sec, 3000 rpm for 30 sec and pattern Cr-Au using cantilever and beam mask.
- 10) Etch Cr-Au using Cr-Au etchant.
- 11) Etch P (VDF-TrFE) by plasma asher simultaneously positive photo resist will be stripped.
- 12) Spin positive photo resist on front side at the rate of 300 rpm for 10 sec, 3000 rpm for 30 sec and pattern Cr-Au using contacts mask.
- 13) Etch Cr-Au using Cr-Au etchant.
- 14) Strip positive photo resist by UV exposure and developer.
- 15) Etch SiO<sub>2</sub> from backside by plasma etching to free the beams and cantilevers.

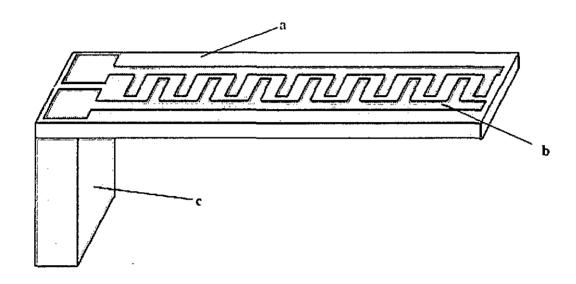
Although the invention has been described with reference to specific embodiments, this description is not meant to be construed in a limiting sense. Various modifications of the disclosed embodiments, as well as alternative embodiments, will be apparent to persons skilled in the art. It is therefore, contemplated that the appended claims will cover all modifications that fall within the true scope of the invention.

- 1. Rashmi K, R
- 2. Jayarama A 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- Shriganesh Prabhu
   Alva's Education Foundation

#### FIGURE 1

Total number of sheets: 14

Number of sheet: 1/14



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Siddhartha P. Duttagupta

Richard Pinto

Alva's Education

Alva's Education Foundation (R).

MOODBIDRI

Śhriganesh Prabhu

13 1 0 7 0 8 / 2 0 1 8 1.4:40

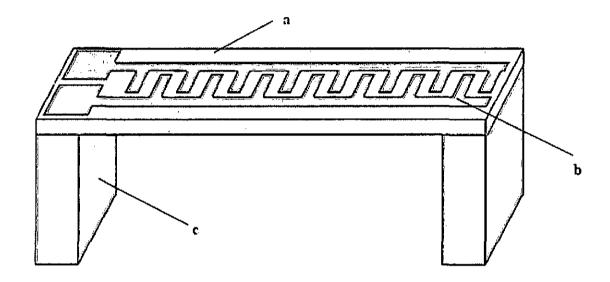
AFEMI OFFICE CHENNAL

- I. Rashmi K. R
- 2. Jayarama A 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

#### FIGURE 2

Total number of sheets: 14

Number of sheet: 2/14



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Richard Pinto

Siddlathe Dongue

Siddhartha P. Duttagupta

Shriganesh Prabhu

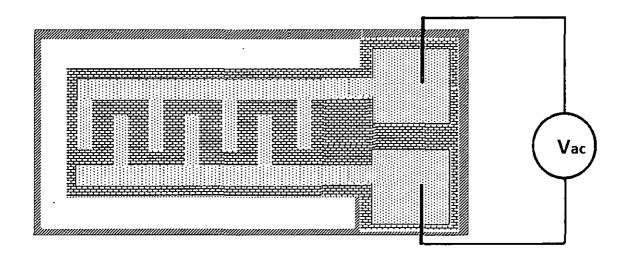
- Applicants:
  1. Rashmi K. R
  2. Jayarama A
  3. Richard Pinto

- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

FIGURE 3

Total number of sheets: 14

Number of sheet: 3/14



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Siddhartha P. Duttagupta

Richard Pinto

Alva's Education Foundation (R).

Chairman

Chairman

Frundation (R).

Alva's Education

Novidibel 574227, D.K.

∕Shriganesh Prabhu

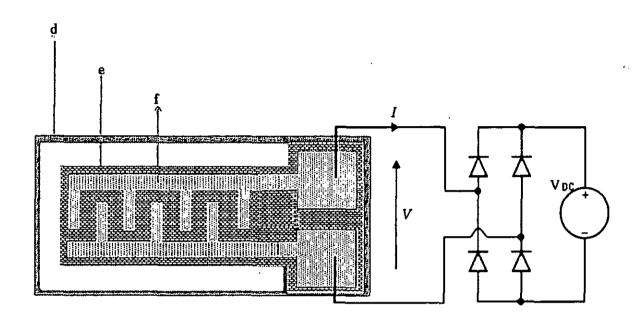
- Applicants:
  1. Rashmi K, R
  2. Jayarama A
  3. Richard Pinto

- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

#### FIGURE 4

Total number of sheets: 14

Number of sheet: 4/14



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Siddhartha P. Duttagupta

Linear Dia

Shriganesh Prabhu

Richard Pinto

Alva's Education Foundation

andation (R). MOODBIURI - 5742 27, D.K.

- I. Rashmi K. R
- 2. Jayarama A 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

FIGURE 5 (a)

Total number of sheets: 14

Number of sheet: 5/14

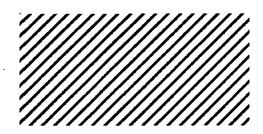
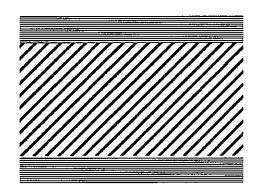


FIGURE 5 (b)



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Siddhartha P. Duttagupta

✓Shriganesh Prabhu

Alva's Education Foundation

Unairman
Unairman
Foundation (R)

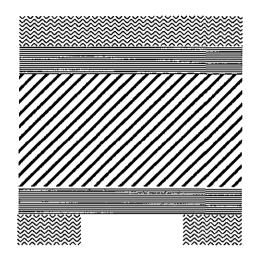
Mais Education Foundation (R)
MOODULIRI - 5: 4227, D.K.

- 1. Rashmi K. R
- Jayarama A
   Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

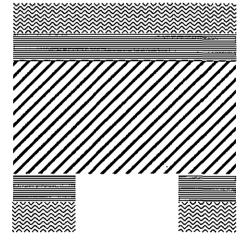
#### FIGURE 5 (c)

Total number of sheets: 14

Number of sheet: 6/14



#### FIGURE 5 (d)



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Richard Pinto

Siddhartha P. Duttagupta

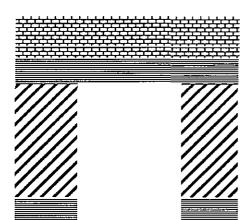
Shriganesh Prabhu

Alva's Education Foundation

Chairman
Chairman
Alva's Education Foundation (R) MOUDBIURI 574227, D.K.

- 1. Rashmi K. R
- 2. Jayarama A 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

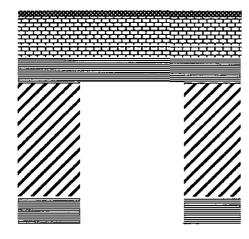
#### FIGURE 5 (g)



Total numbers of sheets: 14

Number of sheet: 8/14

#### FIGURE 5 (h)



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Richard Pinto

Siddhartha P. Duttagupta

Shriganesh Prabhu

Alva's Education Foundation

Chairman

Chairman

Alva's Education Foundation (R)

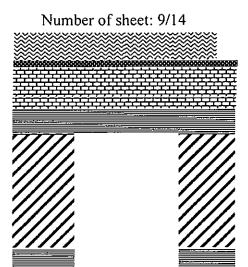
Alva's Education Foundation (R)

- Applicants: 1. Rashmi K. R
- 2. Jayarama A 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu6. Alva's Education Foundation

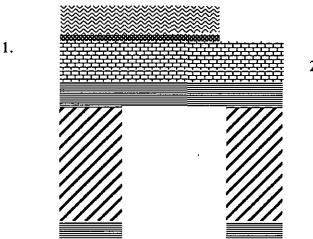
#### FIGURE 5 (i)

1.

Total number of sheets: 14

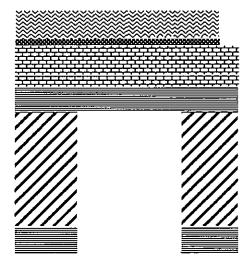


#### FIGURE 5 (j)



2.

2.



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Jayarama A

Richard Pinto

Siddhartha P. Duttagupta

Shriganesh Prabhu

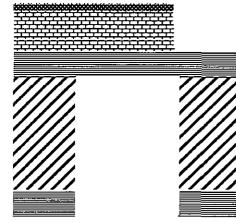
Alva's Education Foundation

Chairman House Foundation (R)

- I. Rashmi K. R
- 2. Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

#### FIGURE 5 (k)

1.



Total numbers of sheets: 14

Number of sheet: 10/14

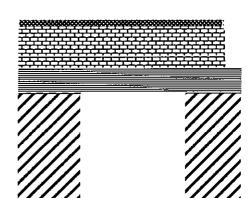
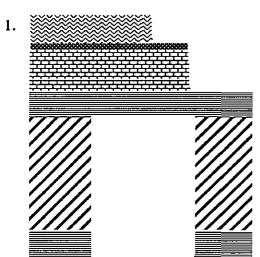
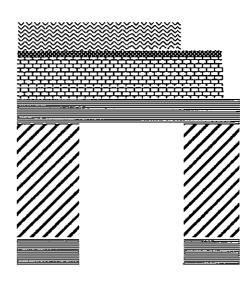


FIGURE 5 (I)



2.

2.



Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Siddlatt Orlan

Siddhartha P. Duttagupta

Shriganesh Prabhu

Richard Pinto

Alva's Education Foundation

Chairman

Chairman

Chairman

Alva F ducation Foundation (R)

DBIDRI - 57 1227, D.K.

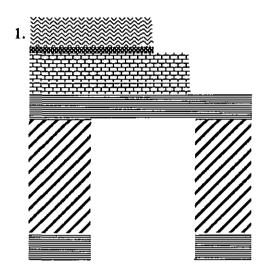
- Applicants:
  1. Rashmi K. R
  2. Jayarama A
  3. Richard Pinto

- 4. Siddhartha P. Duttagupta
- Shriganesh Prabhu
   Alva's Education Foundation

#### FIGURE 5 (m)

Total number of sheets: 14

Number of sheet: 11/14



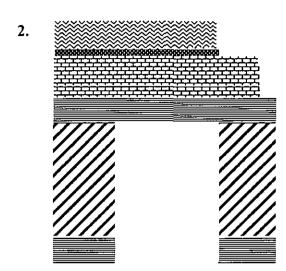
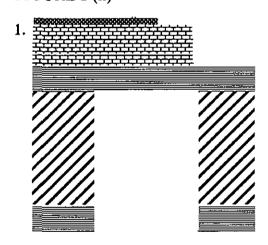
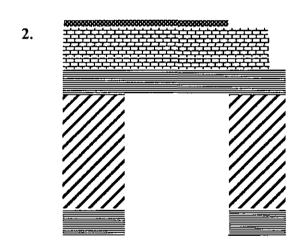


FIGURE 5 (n)





Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Siddhartha P. Duttagupta

Shriganesh Prabhu

Richard Pinto

Alva's Education Foundations Chairm

Chairman
Chairman
Foundation (R)
MOCOUNDATE 574227, D.K. 

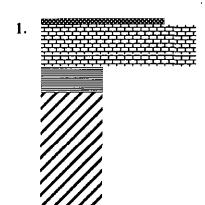
<u>ele ehenmal</u>

- I. Rashmi K. R
- 2. Jayarama A 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

FIGURE 5 (o)

Total number of sheets: 14

Number of sheet: 12/14



2.

Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Siddhartha P. Duttagupta

Jayarama A

Shriganesh Prabhu

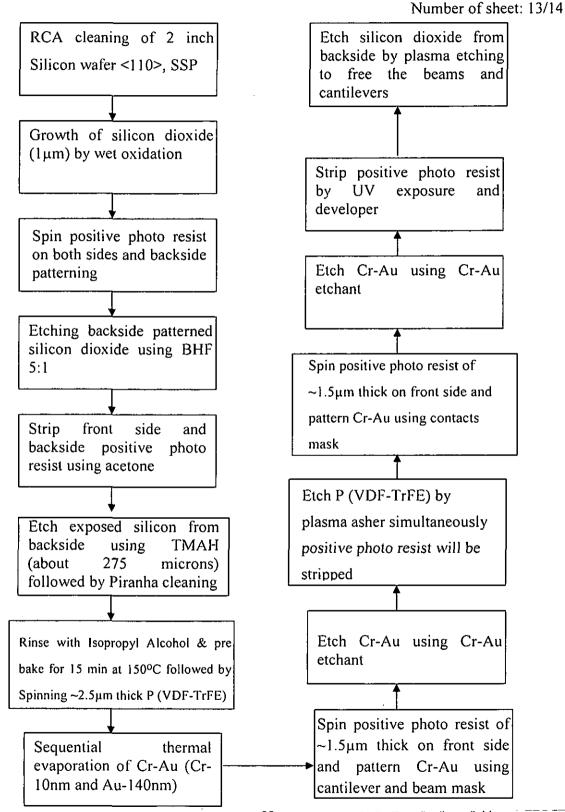
Alva's Education Foundation
Chairman
Foundation

Alva's Education Foundation (R).
MOODENURI - 574227, D.K.

Richard Pinto

- I. Rashmi K, R
- 2. Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

Figure 6



CEPAIL REFERENCES

1261 正面各工法好生品。1.45 4.以

Total number of sheets: 14

- Applicants:
- 1. Rashmi K. R
- 2. Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- 6. Alva's Education Foundation

Total number of sheets: 14

Number of sheet: 14/14

Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Rashmi K. R

Jayarama A

Richard Pinto

Siddhartha P. Duttagupta

Shriganesh Prabhu

Alva's Education Foundation airm

Alva's Education ( S74227, D.K.

- Applicants:
- 1. Rashmi K, R
- 2. Jayarama A
- 3. Richard Pinto
- 4. Siddhartha P. Duttagupta
- 5. Shriganesh Prabhu
- Snnganesh Prabhu
   Alva's Education Foundation

#### WE CLAIM

- 1. A process for fabrication of poly(vinylidenefluoride-co-trifluoroethylene) piezoelectric beams and cantilevers as vibration sensors and energy harvesters comprising:
  - a. Cleaning of Silicon wafers;
  - b. Growing of SiO<sub>2</sub> by wet oxidation;
  - c. Spinning positive photo resist on both sides and backside patterning;
  - d. Etching backside patterned SiO<sub>2</sub> using buffered hydrofluoric acid;
  - e. Stripping front side and back side of positive photo resist using acetone;
  - f. Etching silicon by means of Tetra Methyl Ammonium Hydroxide;
  - g. Piranha cleaning;
  - h. Rinsing with isopropyl alcohol and pre baking for 15 min at 150°C;
  - i. Spinning the said poly (vinylidenefluoride-co-trifluoroethylene);
  - j. Deposition of Cr-Au by sequential thermal evaporation;
  - k. Spinning of positive photo resist on front side;
  - I. Patterning Cr-Au using cantilever and beam mask;
  - m. Etching Cr-Au using Cr-Au etchant;

- Rashmi K. R Javarama A
- 3. Richard Pinto
- Siddhartha P. Duttagupta
- Shriganesh Prabhu
- Alva's Education Foundation
  - Etching poly (vinylidenefluoride-co-trifluoroethylene) using plasma asher;
  - Spinning of positive photo resist on front side;
  - Patterning Cr-Au using contacts mask;
  - Etching Cr-Au using Cr-Au etchant;
  - Stripping positive photo resist by UV exposure and developer; and
  - Etching backside SiO<sub>2</sub> by plasma etching to free the beams and cantilevers.
- 2. The process as claimed in claim 1, wherein the said piranha cleaning is done by mixing sulfuric acid and hydrogen peroxide in 3:1 ratio.
- 3. The process as claimed in claim 1, wherein the said spinning of poly (vinylidenefluorideco-trifluoroethylene) is done at least at 300 rpm for 10 sec and 1000 rpm for 30 sec and spinning of positive photo resist is done at least at 3000 rpm for 30 sec.

Dated this 23<sup>RD</sup> day of JULY, 2018

Signature(s)

Siddhartha P. Duttagupta

Shriganesh Prabhu

Alva's Education Foundation

Alva's Education Foundation (R) MOODBIDRI - STALLT D.K.

#### FORM 5 THE PATENTS ACT, 1970 (38 OF 1970)



The Patents Rules, 2003 STATEMENT AND UNDERTAKING UNDER SECTION 8 (See section 8 rule 12)

We. ALVA'S EDUCATION FOUNDATION, RASHMI K. R, JAYARAMA A and RICHARD PINTO addressed at ALVA'S **ENGINEERING** AND TECHNOLOGY, INSTITUTE OF SHOBHAVANA CAMPUS, MIJAR, MOODBIDRI, DAKSHINA KANNADA - 574225, KARNATAKA, INDIA, SIDDHARTHA P. INSTITUTE DUTTAGUPTA addressed at. INDIAN POWAI, **MUMBAI** TECNOLOGY BOMBAY, SHRIGANESH and MAHARASHTRA. INDIA INSTITUTE **FUNDAMENTAL** addressed OF at TATA RESEARCH, MUMBAI - 400005, MAHARASHTRA, INDIA do hereby declare that to the best of our knowledge, information and belief that the fact and matters stated herein are correct and we request that a patent may be granted to us for the said invention.

Dated this the 23rd day of July, 2018

Signatures

Chairman

Alva's Education Foundation (R) MOODBIDRI - 574227, D.K.

Alva's Education Foundation

avarama A

Richard Pinto

Siddhartha P. Duttagupta

Śhriganesh Prabhu



#### FORM 9

THE PATENTS ACT, 1970 (39 of 1970)

REQUEST FOR EARLY PUBLICATION [See section 11A(2); rule 24A]

CBR: 35519

DATE: 11/12/2018

Axt: 13750/-

We, ALVA'S EDUCATION FOUNDATION, addressed at ALVA'S INSTITUTE OF ENGINEERING AND TECHNOLOGY

SHOBHAVANA CAMPUS, MIJAR, MOODBIDRI, DAKSHINA KANNADA - 574225, KARNATAKA, INDIA hereby request for early publication of my Patent application No 201841030070 dated 10.08.2018 for the invention A PROCESS FOR FABRICATION OF P[VDF-TrFE] PIEZOELECTRIC BEAMS AND CANTILEVERS AS VIBRATION SENSORS AND ENERGY HARVESTERS under section 11A(2) of the Act.

For ALVA'S EDUCATION FOUNDATION,

Authorized Signatory: 600

Name in full:

mohan Alva

Designation:

Chairman.

Seal:

Chairman

Alva's Education Foundation (R) MOODBIDRI - 574227, D.K.

44 0 cash 27501- R13750/-

December 11, 2018

From

RICHARD PINTO,
Alva's Education Foundation,
Alva's Institute Of Engineering And Technology
Shobhavana Campus, Mijar, Moodbidri,
Dakshina Kannada - 574225, Karnataka, India
Email: ariv@leintelligensia.com

D /89435

To

The Controller of Patents, The Patents Office, Guindy, Chennai – 600032.

Sir.

Ref Request for earlier publication of patent applications-reg

We write with reference to the following patent applications.

- 1. Patent application No 201841030070 dated 10.08.2018 for the invention "A PROCESS FOR FABRICATION OF P[VDF-TrFE] PIEZOELECTRIC BEAMS AND CANTILEVERS AS VIBRATION SENSORS AND ENERGY HARVESTERS" under the name ALVA'S EDUCATION FOUNDATION
- 2. Patent application No 201841040380 dated 26.10.2018 for the invention "ENHANCEMENT OF MICRO DIRECT METHANOL FUEL CELL (μ-DMFC) PERFORMANCE USING MICRO CHANNELS FABRICATED FROM <100> SILICON WAFER ORIENTATION AND P(VDF-TrFE) COATED NAFION MEMBRANE AS PROTON EXCHANGE MEMBRANE" under the name ALVA'S EDUCATION FOUNDATION

We submit a request for early publication (Form 9) for each of the above patent applications with sum of Fee Rs.27500/- (Rupees Twenty Seven Thousand and Five Hundred Only). We request you to take the above on record.

Thanking You,

Yours faithfully,

RICHARD PINTO

Encl As above.

ATENT OFFICE CHENNAL 1271272018 14.27

R8800/-

From.

M/S.ALVA'S EDUCATION FOUNDATION, SHOBHAVANA CAMPUS, MIJAR, MOODBIDRI, DAKSHINA KANNADA - 574225 KARNATAKA, INDIA

D 58122

10TH AUGUST 2018

700164395

To

The Controller of Patents, Patents Office, Guindy, Chennai – 600032.

Sir,

Sub: Application for filing Patent Rights-Reg. – Complete Specification.

Referring to the above, we are enclosing **application for request for Complete Specification** along with fee Rs.8800/- (Eight Thousand eight Hundred only) by cash.

The Title of the Patent is as follows:

1. A PROCESS FOR FABRICATION OF PIEZOELECTRIC BEAMS AND CANTILEVERS AS VIBRATION SENSORS AND ENERGY HARVESTERS.
Kindly Acknowledge the same.

Thanking You,

Yours faithfully

RRinto

RICHARD PINTO(INVENTOR)

Encl:

1. Patent Applications Form - 1,3,5 & 2, Abstract, Drawings & Claims